

Preliminary Data Sheet No. PD60062 revN (NOTE:For new designs, we recommend IR's new product IRS2153(D) IR2153(D)(S)&(PbF)

# SELF-OSCILLATING HALF-BRIDGE DRIVER

#### Features

- Integrated 600V half-bridge gate driver
- 15.6V zener clamp on Vcc
- True micropower start up
- Tighter initial deadtime control
- Low temperature coefficient deadtime
- Shutdown feature (1/6th Vcc) on C<sub>T</sub> pin
- Increased undervoltage lockout Hysteresis (1V)
- Lower power level-shifting circuit
- Constant LO, HO pulse widths at startup
- Lower di/dt gate driver for better noise immunity
- Low side output in phase with R⊺
- Internal 50nsec (typ.) bootstrap diode (IR2153D)
- Excellent latch immunity on all inputs and outputs
- ESD protection on all leads
- Also available LEAD-FREE

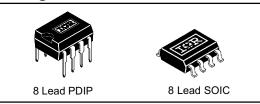
#### Description

The IR2153D(S) are an improved version of the popular IR2155 and IR2151 gate driver ICs, and incor-

#### Product Summary

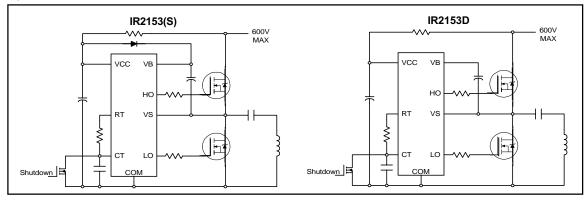
VOFFSET	600V max.
Duty Cycle	50%
Tr/Tp	80/40ns
V <sub>clamp</sub>	15.6V
Deadtime (typ.)	1.2 µs

#### Packages



porates a high voltage half-bridge gate driver with a front end oscillator similar to the industry standard CMOS 555 timer. The IR2153 provides more functionality and is easier to use than previous ICs. A shutdown feature has been designed into the CT pin, so that both gate driver outputs can be disabled using a low voltage control signal. In addition, the gate driver output pulse widths are the same once the rising undervoltage lockout threshold on V<sub>CC</sub> has been reached, resulting in a more stable profile of frequency vs time at startup. Noise immunity has been improved significantly, both by lowering the peak di/dt of the gate drivers, and by increasing the undervoltage lockout hysteresis to 1V. Finally, special attention has been payed to maximizing the latch immunity of the device, and providing comprehensive ESD protection on all pins.

#### **Typical Connections**



# IR2153(D)(S)& (PbF)

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#### **Absolute Maximum Ratings**

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM, all currents are defined positive into any lead. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition	Min.	Max.	Units		
VB	High side floating supply voltage	-0.3	625			
VS	High side floating supply offset voltage		V <sub>B</sub> - 25	V <sub>B</sub> + 0.3		
V <sub>HO</sub>	High side floating output voltage		V <sub>S</sub> - 0.3	V <sub>B</sub> + 0.3		
V <sub>LO</sub>	Low side output voltage		-0.3	V <sub>CC</sub> + 0.3	V	
V <sub>RT</sub>	R <sub>T</sub> pin voltage		-0.3	V <sub>CC</sub> + 0.3		
V <sub>CT</sub>	C <sub>T</sub> pin voltage		-0.3	V <sub>CC</sub> +0.3		
lcc	Supply current (note 1)		—	25	mA	
I <sub>RT</sub>	R <sub>T</sub> pin current		-5	5		
dV <sub>s</sub> /dt	Allowable offset voltage slew rate	owable offset voltage slew rate		50	V/ns	
PD	Maximum power dissipation @ $T_A \le +25^{\circ}C$ (8 Lead DIP)		—	1.0	w	
	(8 Lead SOIC)		—	0.625	vv	
Rth <sub>JA</sub>	Thermal resistance, junction to ambient (8 Lead DIP)		—	125	°C/W	
	(8 Lead SOIC)		_	200	°C/W	
TJ	Junction temperature	nction temperature				
Τ <sub>S</sub>	Storage temperature	-55	150	°C		
ΤL	Lead temperature (soldering, 10 seconds)	nperature (soldering, 10 seconds)				

#### **Recommended Operating Conditions**

For proper operation the device should be used within the recommended conditions.

Symbol	Definition	Min.	Max.	Units
V <sub>BS</sub>	High side floating supply voltage	V <sub>CC</sub> - 0.7	VCLAMP	
Vs	Steady state high side floating supply offset voltage	-3.0 (note 2)	600	V
V <sub>CC</sub>	Supply voltage	10	V <sub>CLAMP</sub>	
Icc	Supply current	(note 3)	5	mA
ТJ	Junction temperature	-40	125	°C

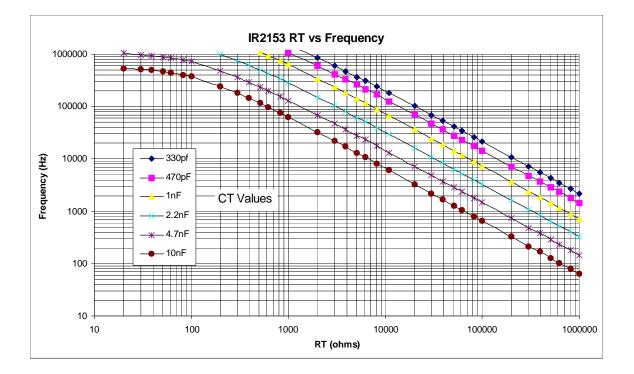
Note 1: This IC contains a zener clamp structure between the chip V<sub>CC</sub> and COM which has a nominal breakdown voltage of 15.6V. Please note that this supply pin should not be driven by a DC, low impedance power source greater than the V<sub>CLAMP</sub> specified in the Electrical Characteristics section.

Note 2: Care should be taken to avoid output switching conditions where the V<sub>S</sub> node flies inductively below ground by more than 5V.

Note 3: Enough current should be supplied to the V<sub>CC</sub> pin of the IC to keep the internal 15.6V zener diode clamping the voltage at this pin.

#### **Recommended Component Values**

Symbol	Component	Min.	Max.	Units
RT	Timing resistor value	10	_	kΩ
CT	C <sub>T</sub> pin capacitor value	330	_	pF



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#### **Electrical Characteristics**

 $V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ) = 12V,  $C_L$  = 1000 pF,  $C_T$  = 1 nF and  $T_A$  = 25°C unless otherwise specified. The  $V_{IN}$ ,  $V_{TH}$  and  $I_{IN}$  parameters are referenced to COM. The  $V_O$  and  $I_O$  parameters are referenced to COM and are applicable to the respective output leads: HO or LO.

Low Voltage Supply Characteristics						
Symbo	I Definition	Min.	Тур.	Max.	Units	Test Conditions
V <sub>CCUV+</sub>	Rising V <sub>CC</sub> undervoltage lockout threshold	8.1	9.0	9.9		
V <sub>CCUV-</sub>	Falling V <sub>CC</sub> undervoltage lockout threshold	7.2	8.0	8.8	V	
VCCUVH	V <sub>CC</sub> undervoltage lockout Hysteresis	0.5	1.0	1.5	1	
IQCCUV	Micropower startup V <sub>CC</sub> supply current		75	150	μΑ	V <sub>CC</sub> ≤V <sub>CCUV</sub> -
lacc	Quiescent V <sub>CC</sub> supply current	_	500	950	_ μΑ	
VCLAMP	V <sub>CC</sub> zener clamp voltage	14.4	15.6	16.8	V	I <sub>CC</sub> = 5mA
Floatir	ng Supply Characteristics					
Symbo	I Definition	Min.	Тур.	Max.	Units	Test Conditions
IQBSUV	Micropower startup V <sub>BS</sub> supply current	_	0	10		V <sub>CC</sub> ≤V <sub>CCUV</sub> -
I <sub>QBS</sub>	Quiescent VBS supply current	_	30	50	μΑ	
VBSMIN	Minimum required V <sub>BS</sub> voltage for proper	_	4.0	5.0	V	V <sub>CC</sub> =V <sub>CCUV+</sub> + 0.1V
	functionality from R <sub>T</sub> to HO					
I <sub>LK</sub>	Offset supply leakage current	_	_	50	μA	$V_{\rm B} = V_{\rm S} = 600 V$
VF	Bootstrap diode forward voltage (IR2153D)	0.5	_	1.0	V	IF = 250mA
	tor I/O Characteristics	Min.	Тур.	Max.	Units	Test Conditions
fosc	Oscillator frequency	19.4	20	20.6		R <sub>T</sub> = 36.9kΩ
1050		94	100	106	kHz	$RT = 7.43k\Omega$
d	RT pin duty cycle	48	50	52	%	fo < 100kHz
ICT	CT pin current		0.001	1.0	uA	
ICTUV	UV-mode CT pin pulldown current	0.30	0.70	1.2	mA	V <sub>CC</sub> = 7V
VCT+	Upper CT ramp voltage threshold		8.0	_		
Vct-	Lower CT ramp voltage threshold	_	4.0	—	V	
VCTSD	CT voltage shutdown threshold	1.8	2.1	2.4	1	
V <sub>RT+</sub>	High-level RT output voltage, VCC - VRT		10	50		I <sub>RT</sub> = 100μA
		—	100	300		I <sub>RT</sub> = 1mA
Vrt-	Low-level RT output voltage		10	50	1	I <sub>RT</sub> = 100μA
		—	100	300	mV	I <sub>RT</sub> = 1mA
Vrtuv	UV-mode RT output voltage	_	0	100	IIIV	V <sub>CC</sub> ≤V <sub>CCUV</sub> -
Vrtsd	SD-Mode RT output voltage, VCC - VRT	—	10	50	1	I <sub>RT</sub> = 100μA,
						$V_{CT} = 0V$
	1 +				Т	
		_	10	300		I <sub>RT</sub> = 1mA, V <sub>CT</sub> = 0V



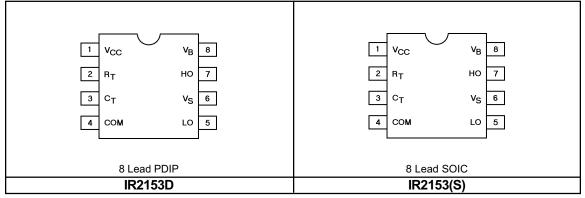
# **Electrical Characteristics (cont.)**

Gate D	Gate Driver Output Characteristics					
Symbol	Definition	Min.	Тур.	Max.	Units	<b>Test Conditions</b>
VOH	High level output voltage, VBIAS -VO		0	100		I <sub>O</sub> = OA
VOL	Low-level output voltage, VO	_	0	100	mV	I <sub>O</sub> = OA
VOL_UV	UV-mode output voltage, VO	—	0	100		I <sub>O</sub> = OA
						I <sub>O</sub> = OA V <sub>CC</sub> ≤V <sub>CCUV</sub> -
tr	Output rise time	_	80	150		
tf	Output fall time	_	45	100	nsec	
t <sub>sd</sub>	Shutdown propogation delay	_	660	—		
t <sub>d</sub>	Output deadtime (HO or LO)	0.75	1.20	1.65	μsec	

### **Lead Definitions**

Symbol	Description
Vcc	Logic and internal gate drive supply voltage
R <sub>T</sub>	Oscillator timing resistor input
CT	Oscillator timing capacitor input
COM	IC power and signal ground
LO	Low side gate driver output
VS	High voltage floating supply return
НО	High side gate driver output
VB	High side gate driver floating supply

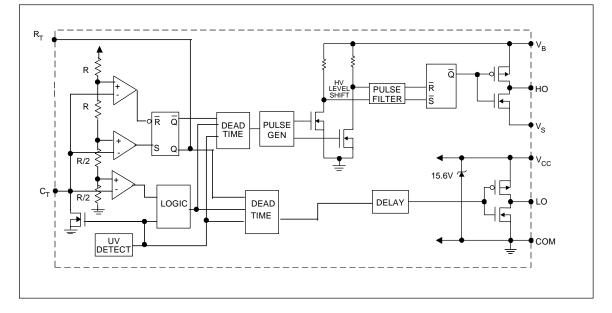
#### Lead Assignments



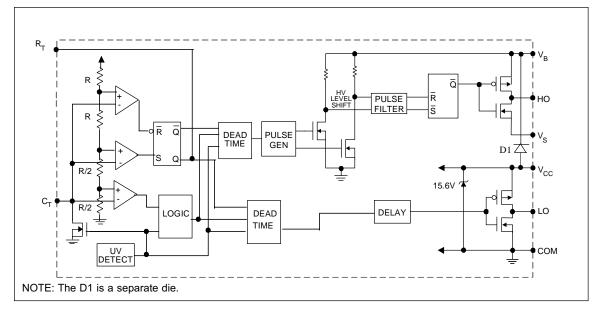
NOTE: The IR2153D is offered in 8 lead PDIP only.

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# Functional Block Diagram for IR2153(S)



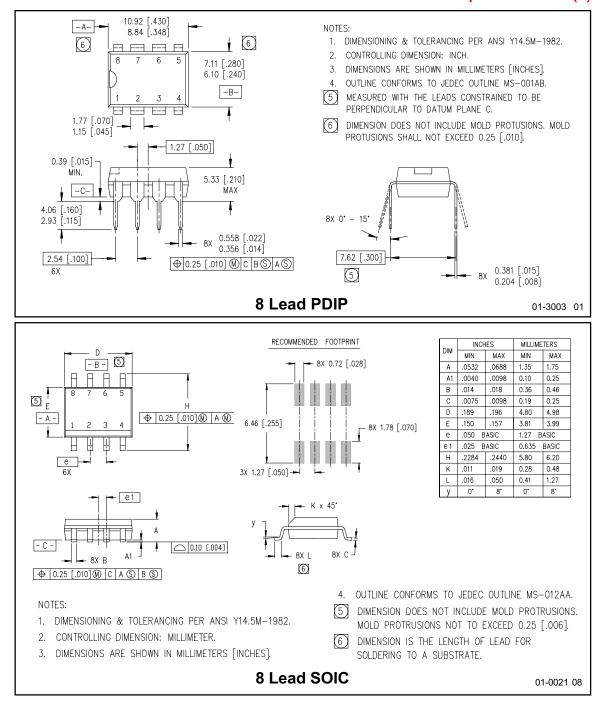
# Functional Block Diagram for IR2153D



# International

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#### IR2153(D)(S) & (PbF) NOTE:For new designs, we recommend IR's new product IRS2153(D)



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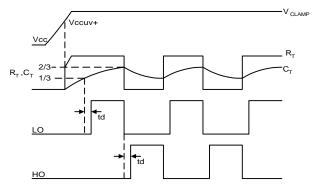


Figure 1. Input/Output Timing Diagram

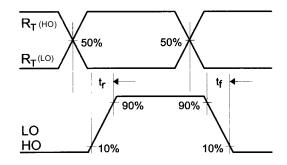


Figure 2. Switching Time Waveform Definitions

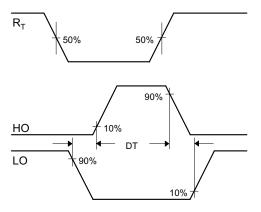
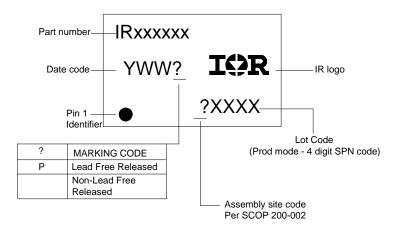


Figure 3. Deadtime Waveform Definitions

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#### LEADFREE PART MARKING INFORMATION



#### **ORDER INFORMATION**

Basic Part (Non-Lead Free)

8-Lead PDIP IR2153 order IR2153 8-Lead SOIC IR2153S order IR2153S 8-Lead PDIP IR2153D order IR2153D

#### Leadfree Part

8-Lead PDIP IR2153 order IR2153PbF 8-Lead SOIC IR2153S order IR2153SPbF 8-Lead PDIP IR2153D order IR2153DPbF

International IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245 Tel: (310) 252-7105 This product has been qualified per industrial level Data and specifications subject to change without notice. 11/16/2005